

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A production method of a multilayer ceramic device, comprising the steps of:
  - forming a green sheet by using a green sheet slurry;
  - forming an electrode pattern layer on said green sheet;
  - forming a dielectric blank pattern layer on level difference gap portion on said electrode pattern layer so as to bury the level difference on said pattern electrode layer by using an electrode level difference absorbing dielectric paste;
  - forming a multilayer body by stacking a plurality of stacking units, wherein the stacking unit is said green sheet formed with said dielectric blank pattern layer and said electrode pattern layer; and
  - firing said multilayer body;
- wherein:
  - said green sheet slurry includes a first inorganic dielectric colorant powder and a first organic binder component;
  - said electrode level difference absorbing dielectric paste includes a second inorganic dielectric colorant powder and a second organic binder component; and
  - when a first weight ratio of the first organic binder component with respect to said first inorganic dielectric colorant powder in said green sheet slurry is (A), and a second weight ratio of the second organic binder component with respect to said second inorganic dielectric colorant powder in said electrode level difference absorbing dielectric paste is (B),
  - said second weight ratio (B) is larger than said first weight ratio (A).

2. (Original) The production method of a multilayer ceramic device as set forth in claim 1, wherein a thickness of said green sheet is made to be 3 $\mu$ m or thinner.

3. (Currently Amended) The production method of a multilayer ceramic device as set forth in claim 1 ~~or 2~~, wherein said first organic binder component and/or second organic binder component are a polymeric resin and a plasticizer.

4. (Original) The production method of a multilayer ceramic device as set forth in claim 3, wherein said second weight ratio (B) in the electrode level difference absorbing dielectric paste is 5 to 40 wt%, and a weight ratio of said polymeric resin is 10 wt% or less with respect to said inorganic dielectric colorant powder.

5. (Currently Amended) The production method of a multilayer ceramic device as set forth in ~~any one of claims 1 to 4~~ claim 1, wherein a value (B-A) obtained by subtracting said first weight ratio (A) from said second weight ratio (B) is 1.5 or larger.

6. (Currently Amended) A multilayer ceramic device obtained by any one of the production methods as set forth in claim 1 ~~to 5~~.

7. (Original) The multilayer ceramic device as set forth in claim 6, wherein an interlayer thickness is 2.5 $\mu$ m or thinner.

8. (New) The production method of a multilayer ceramic device as set forth in claim 2, wherein said first organic binder component and/or second organic binder component are a polymeric resin and a plasticizer.

9. (New) The production method of a multilayer ceramic device as set forth in claim 2, wherein a value  $(B-A)$  obtained by subtracting said first weight ratio (A) from said second weight ratio (B) is 1.5 or larger.

10. (New) The production method of a multilayer ceramic device as set forth in claim 3, wherein a value  $(B-A)$  obtained by subtracting said first weight ratio (A) from said second weight ratio (B) is 1.5 or larger.

11. (New) The production method of a multilayer ceramic device as set forth in claim 4, wherein a value  $(B-A)$  obtained by subtracting said first weight ratio (A) from said second weight ratio (B) is 1.5 or larger.

12. (New) A multilayer ceramic device obtained by any one of the production methods as set forth in claim 2.

13. (New) A multilayer ceramic device obtained by any one of the production methods as set forth in claim 3.

14. (New) A multilayer ceramic device obtained by any one of the production methods as set forth in claim 4.

15. (New) A multilayer ceramic device obtained by any one of the production methods as set forth in claim 5.